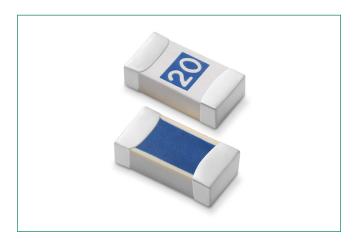
RoHS 🗭 HF c 🔊 us 🏵



Additional Information



Resources

Accessories

Agency Approvals

Agency	Agency File Number	Ampere Range
c SL us	E10480	10A - 20A
۹.	29862	10A - 20A

Electrical Characteristics for Series

% of Ampere Rating	Ampere Rating	Opening Time at 25°C
100%	10A – 20A	4 Hours, Minimum
350%	10A – 20A	5 Seconds, Maximum

Description

The 501A series AECQ-Compliant fuses and Halogen free fuse series are specifically tested to cater to secondary circuit protection needs of compact auto electronics application. The general design ensures excellent temperature stability and performance reliability. The high I2t values which are typical in the Littelfuse Ceramic Fuse family, ensure high inrush current withstanding capability.

Features & Benefits

- Operating Temperature from -55°C to +150°C
- Meets Littelfuse's automotive qualifications*
- 100% Lead-free, RoHS compliant and Halogen-free
- Suitable for both leaded and lead-free reflow/wave soldering
- Recognized to UL/CSA/NMX 248-1 and UL/CSA/NMX 248-14
- * Largely based on Littelfuse internal AEC-Q200 test plan

Applications

- Li-ion Battery
- LED Head-Lights
- Automotive Navigation System
- TFT Display

- Battery Management System (BMS)
- Clusters

Electrical Specifications by Item

Ampere	Amp	Max. Voltage	Interrupting Rating	Nominal	Nominal	Nominal Voltage	Nominal Power	Agency Approvals	
Rating (A)	Code	Rating (V)	(DC) ¹	Resistance (Ohms) ²	Melting I ² t (A ² Sec.) ³	Drop at Rated Current (V) ⁴	Dissipation at Rated Current (W)	c RU us	۹.
10	010.	32	150A @ 32VDC	0.00362	10.385	0.04407	0.4407	х	х
12	012.	32		0.00311	20.341	0.04927	0.5912	х	х
15	015.	32		0.00250	39.700	0.04843	0.7265	х	Х
20	020.	32		0.00194	86.360	0.05888	1.1776	х	х

Notes:

DC Interrupting Rating tested at rated voltage with time constant <0.5msec
Nominal Resistance measured with <10% rated current.

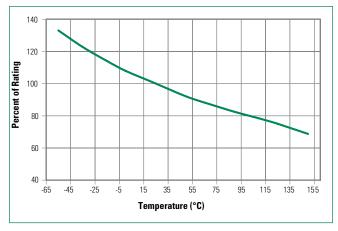
3. Nominal Melting I²t measured at 1 msec. opening time. For other I²t data refer to chart. 4. Nominal Voltage Drop measured at rated current after temperature has stabilized and with fuse mounted on board with 3oz Cu trace.

Devices designed to carry rated current for four hours minimum. It is recommended that devices be operated continuously at no more than 80% rated current. See "Temperature Re-rating Curve" for additional re-rating information

Devices designed to be mounted with marking code facing up.



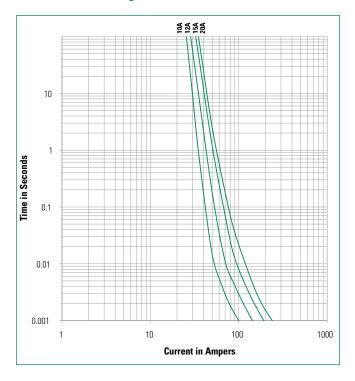
501A Series High Current 1206 Fast-Acting Fuse



Temperature Re-rating Curve

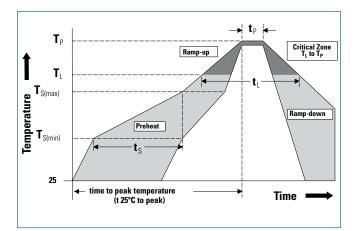
Note: 1. Re-rating depicted in this curve is in addition to the standard re-rating of 20% for continuous operation.

Example: For continuous operation at 75 degrees celsius, the fuse should be rerated as follows: $I = (0.80)(0.85)I_N = (0.68)I_N$



Reflow Condition			Pb – free assembly	
	- Temperature Min (T _{s(min)})		150°C	
Pre Heat	- Temperature Max (T _{s(max)})		200°C	
	-Time (Min to Max) (t _s)		60 – 180 seconds	
Average Ramp-up Rate (Liquidus Temp (T _L) to peak)			3°C/second max.	
T _{S(max)} to T _L - Ramp-up Rate			5°C/second max.	
Reflow	- Temperature (T _L) (Liquidus)		217°C	
nenow	- Temperature (t _L)		60 – 150 seconds	
Peak Temperature (T _P)			260+ ^{0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)			10 – 30 seconds	
Ramp-down Rate			6°C/second max.	
Time 25°C to peak Temperature (T _P)			8 minutes max.	
Do not exceed		260°C		
Wave Soldering		260°C, 10 seconds max.		

Soldering Parameters



Average Time Current Curves

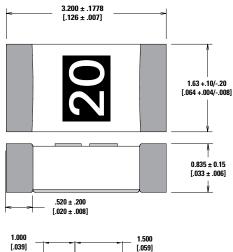
Fuse Datasheet

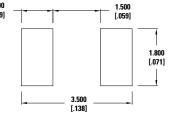
501A Series High Current <u>1206 Fast-Acting Fuse</u>

Product Characteristics

MaterialsTerminations: Ag / Ni / Sn (100% Lead-free) Element Cover Coating: Lead-free GlassMoisture Sensitivity LevelIPC/JEDEC J-STD-020, Level 1SolderabilityIPC/ECA/JEDEC J-STD-002, Condition CHumidity TestMILSTD-202, Method 103, C onditions DResistance to Solder HeatMILSTD-202, Method 210, Condition BMoisture ResistanceMILSTD-202, Method 107, Condition BMechanical ShockMILSTD-202, Method 213, Condition AVibrationMILSTD-202, Method 201, Condition DTerminal StrengthIEC 60127-4High Temperature StorageMILSTD-202, Method 108, with exemptionsThermal Shock TestJESD22 Method JA-104, Test Conditions B and NBiased HumidityMILSTD-202, Method 103, 85°C/85% RH with 10% operating power for 100hrsOperational LifeMILSTD-202, Method 108, rest Condition DResistance to SolventsMILSTD-202, Method 108, rest Condition DMilesTD-202, Method 204MilesTD-202, Method 103, 85°C/85% RH with 10% operating power for 100hrsOperational LifeMILSTD-202, Method 108, rest Condition DResistance to SolventsMILSTD-202, Method 213, rest Condition DMilesTD-202, Method 204MilesTD-202, Method 204MilesTD-202, Method 204MilesTD-202, Method 204Resistance to SolventsMilesTD-202, Method 204MilesTD-202, Method 204 </th <th></th> <th>Body: Advanced Ceramic</th>		Body: Advanced Ceramic		
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Humidity TestMILSTD-202, Method 103, C onditions DResistance to Solder HeatMILSTD-202, Method 210, Condition BMoisture ResistanceMILSTD-202, Method 106Thermal ShockMILSTD-202, Method 107, Condition BMechanical ShockMILSTD-202, Method 213, Condition AVibrationMILSTD-202, Method 201Vibration, High FrequencyMILSTD-202, Method 204, Condition DIPC/ECA/JEDEC J-STD-002, Condition DIPC/ECA/JEDEC J-STD-002, Condition DTerminal StrengthIEC 60127-4High Temperature StorageMILSTD-202, Method 108 with exemptionsJESD22 Method JA-104, Test Conditions B and NMILSTD-202, Method 103, 85°C/85% RH with 10% operating power for 1000hrsOperational LifeMILSTD-202, Method 108, Test Condition DResistance to SolventsMILSTD-202, Method 213, Test Condition CMiles TD-202, Method 213, Test Condition DResistance to SolventsMILSTD-202, Method 204Resistance to Soldering High Frequency VibrationMILSTD-202, Method 213, Test Condition CHigh Frequency VibrationMILSTD-202, Method 204Resistance to Soldering HeatMILSTD-202, Method 204SolderabilityJESD22-B102E Method 1Terminal Strength for SMD Board FlexAEC 0200-005	Moisture Sensitivity Level	IPC/JEDEC J-STD-020, Level 1		
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Biased HumidityRH with 10% operating power for 1000hrsOperational LifeMILSTD-202, Method 108, Test Condition DResistance to SolventsMILSTD-202, Method 215Mechanical ShockMILSTD-202, Method 213, Test Condition CHigh Frequency VibrationMILSTD-202, Method 204Resistance to Soldering HeatMILSTD-202, Method 210, Test Condition BSolderabilityJESD22-B102E Method 1Terminal Strength for SMDAEC Q200-005Board FlexAEC Q200-005				
Operational LifeMILSTD-202, Method 108, Test Condition DResistance to SolventsMILSTD-202, Method 215Mechanical ShockMILSTD-202, Method 213, Test Condition CHigh Frequency VibrationMILSTD-202, Method 204Resistance to Soldering HeatMILSTD-202, Method 210, Test Condition BSolderabilityJESD22-B102E Method 1Terminal Strength for SMD Board FlexAEC Q200-005	Biased Humidity			
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Mechanical ShockMIL-STD-202, Method 213, Test Condition CHigh Frequency VibrationMIL-STD-202, Method 204Resistance to Soldering HeatMIL-STD-202, Method 210, Test Condition BSolderabilityJESD22-B102E Method 1Terminal Strength for SMD Board FlexAEC 0200-006	Desistance to Columnts			
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Resistance to Soldering HeatMILSTD-202, Method 210, Test Condition BSolderabilityJESD22-B102E Method 1Terminal Strength for SMD Board FlexAEC Q200-006	Mechanical Shock			
Heat Test Condition B Solderability JESD22-B102E Method 1 Terminal Strength for SMD AEC Q200-006 Board Flex AEC Q200-005	High Frequency Vibration	MIL-STD-202, Method 204		
Terminal Strength for SMD AEC Q200-006 Board Flex AEC Q200-005				
Board Flex AEC Q200-005	Solderability	JESD22-B102E Method 1		
	Terminal Strength for SMD	AEC Q200-006		
Electrical Characterization Three Temperature Electrical	Board Flex	AEC Q200-005		
	Electrical Characterization	tion Three Temperature Electrical		

Dimensions (mm)





Part Marking System

Part Numbering System

Amp Code	Marking Code
010.	10
012.	12
015.	15
020.	20

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity and Packaging Code
8mm Tape and Reel	EIA-481, IEC 60286, Part 3	3000	WR

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